

# Microelectronics Fabrication Center

Your Solution for Fabrication  
and Assembly Needs

Services  
Brochure



## Your Solution for Fabrication and Assembly Needs

Anritsu Microelectronics Fabrication Center, conveniently located south of Silicon Valley in Morgan Hill, CA, includes a 8000 sqft class 100/10,000 clean room, a 25,000 sq. ft. RF/Microwave assembly manufacturing facility, and a state of the art machining center. We are proud to be your partner for thin film device fabrication, microelectronic assembly, packaging, and machining.

### QUALITY

Custom Thin Film Devices  
GaAs/InP Optoelectronics Wafer Foundry  
MEMs  
Rapid Prototyping

### RELIABILITY

High Volume High Quality Production  
Process Engineering Support  
Microelectronic Assembly  
Testing and Machining

### FLEXIBILITY



#### Thin Film Fab

##### Photolithography

5x stepper, contact lithography, double sided aligning available

##### Etching

Plasma, RIE, wet etching of metal, silicon, nitride, and oxide

##### Dielectric Deposition

Plasma-Enhanced CVD

##### Metal Deposition

Sputtering, E-Beam Evaporation

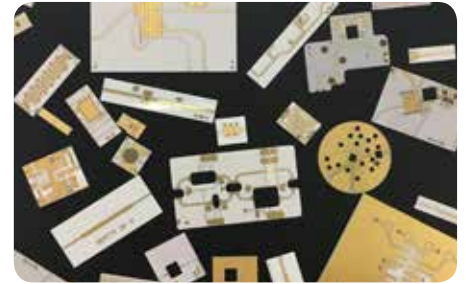
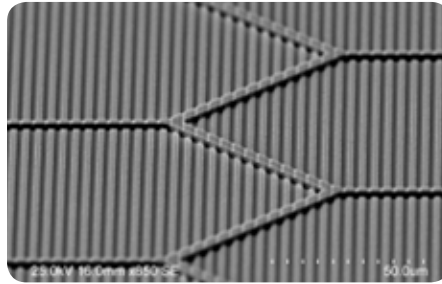
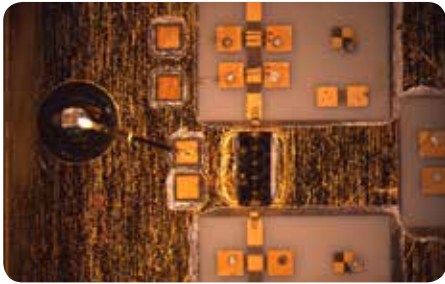
##### Other Process Capabilities

Selective gold and AuSn electroplating  
Polyimide, BCB, and Si<sub>3</sub>N<sub>4</sub> Capacitors  
Integrated Resistors  
Filled and Plated Through vias  
Wrap-arounds  
Precision Laser Resistor Trimming  
Full Support Custom Product Development

##### Material

Alumina, Aluminum Nitride, Fused Silica, Sapphire, Glass, Silicon, GaAs and InP wafers, CVD Diamond, etc.

Anritsu Company is a global leader in RF/Microwave test and measurement equipment for laboratories and field applications.



• **CONVENIENCE**

• **QUICK DELIVERY**

**Markets Served**

- Telecommunications
- Civil Aviation and Aerospace
- Automotive
- Defense
- Biotechnology and Medical
- Solar



**Microelectronic Manufacturing**

**Assembly Equipment and capabilities**

Auto Wedge Bonder, SEM, Acoustic Microscope, Eutectic Die Attach, Epoxy Die Attach, Gap Welding, Wedge Bonding, Tack Bonding, Ball Bonding, Sheet Epoxy Attach, Non-conductive Epoxy Attach, Hermetically Sealed Connector Assembly, Soldering (*AuSn, Indium, SnPb, Gold Germanium, RoHs Compliant solders available*)

**Testing**

DC-145GHz range, S Parameters, Noise figure, Noise Floor, Dynamic range, IIP3/OIP3, Harmonic levels, Phase noise

**Reliability Testing**

IC thermal imaging, Material Analysis, HALT and HASS testing, Environmental testing, Burn-in, Power Cycling, EMI/EMC testing, Drop testing, Die Attach Void testing, Temperature Cycle with or without testing, shear and pull testing

**Machining**

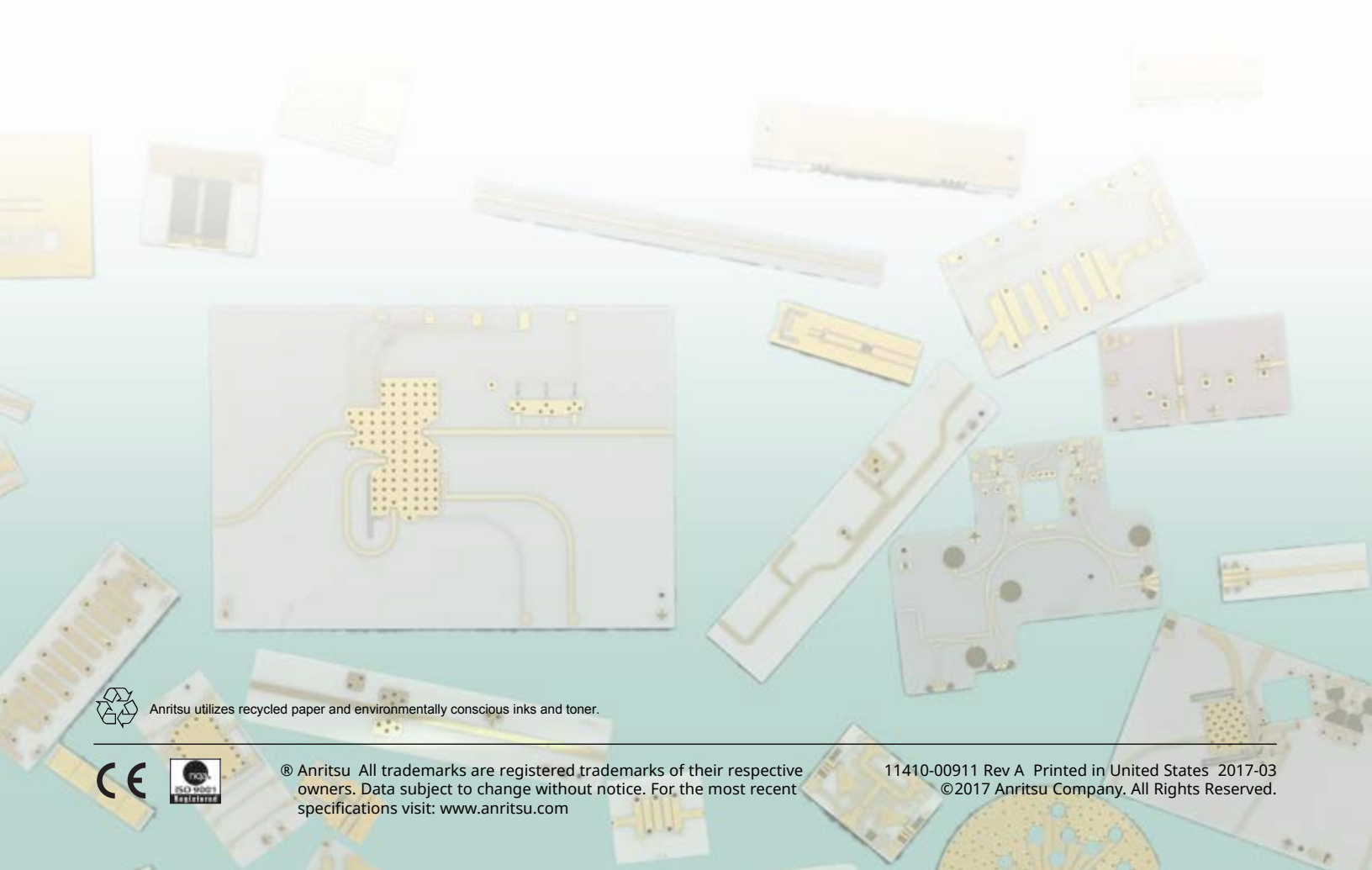
CNC and manual Mills and Lathes

Anritsu Company is the United States subsidiary of Anritsu Corporation, a global provider of innovative communications test and measurement solutions for 120 years. Anritsu's "2020 VISION" philosophy engages customers as true partners to help develop wireless, optical, microwave/RF, and digital instruments, as well as operation support systems for R&D, manufacturing, installation, and maintenance applications.

Anritsu also provides precision microwave/RF components, optical devices, and high-speed electrical devices for communication products and systems.

The company develops advanced solutions for 5G, M2M, IoT, as well as other emerging and legacy wired and wireless applications. With offices throughout the world with approximately 4000 employees, Anritsu's products are sold in over 90 countries.

To learn more about our services, please email us at [Microelectronics@Anritsu.com](mailto:Microelectronics@Anritsu.com)



Anritsu utilizes recycled paper and environmentally conscious inks and toner.



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